

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20191010001.1 Qualification of new Bump site and BOM for select devices

Change Notification / Sample Request

Date: October 10, 2019

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN_ww_admin_team@list.ti.com</u>). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team SC Business Services

20191010001.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS7886SBDCKT	null
ADS8319IDGST	null
ADS8339IDGST	null
ADS8319IBDGSR	null
ADS7886SBDCKR	null
ADS8339IDGSR	null
ADS7883SBDBVT	null
ADS7888SDCKT	null
ADS8319IBDGST	null
ADS7884SDBVT	null
ADS8318IDGSR	null
ADS7886SDCKT	null
ADS7888SDCKR	null
ADS7887SDBVR	null

Technical details of this Product Change follow on the next page(s).

Title: Qualification of new Bump site and BOM for select devices Customer Contact: PCN Manager Dept: Quality Services	PCN I	CN Number: 20191010001.1 PCN Date: Oct 10 2019						019						
Proposed 1st Ship Date: Jan 10 2020 Estimated Sample Availability: Sample request	Title:	Title: Qualification of new Bump site and BOM for select devices												
Change Type:	Custo	Customer Contact: PCN Manager Dept: Quality Services												
Assembly Site	Proposed 1 st Ship Date: Jan 10			0 20	020	Est					•	t		
□ Assembly Site □ Design □ Wafer Bump Site □ Assembly Materials □ Part number change □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Mechanical Specification □ Test Site □ Wafer Fab Site □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Wafer Fab Process □ Wafer Fab Materials □ Wafer Fab Process □ Wafer Fab Materials □ Wafer Fab Process □ Wafer Pab Process □ Wafer Fab Process □ Wafer Fab Process □ Wafer Pab Process □ Waf	Chan	ge Type:							Ava	IIaL	ility.	Samp	ne request	
Assembly Materials			9				Design			\boxtimes	Wafer	Bum	p Site	
Mechanical Specification	A	Assembly Pro	cess				Data S	heet		\boxtimes	Wafer	Bum	p Material	
PCN Details PCN Details PCN Details PCN Details PCN is to inform of a new bump site and BOM for the devices listed in the product affected section below as follows: What									e					
PCN Details Description of Change: This PCN is to inform of a new bump site and BOM for the devices listed in the product affected section below as follows: What Current New Bump Site AT5 JCAP Bump Composition Hi Pb Cu/AgSn Die Coat None PI Lead finish (ADS7883/4/5, & DGS devices only) NiPdAu Matte Sn ECAT E3, G4 or E4 G3 or G4 Reason for Change: Continuity of Supply Anticipated impact on Material Declaration None Anticipated impact on Material Declaration No Impact to the Material Declaration Supply Alterial Declaration or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website. Changes to product identification resulting from this PCN: None Product Affected: ADS7883SDBVR ADS7886SBDCKR ADS7888SDBVR ADS8319IBDGSR ADS7883SDBVR ADS7888SDBVR ADS7888SDDKR ADS7888SDBVR ADS7888SDBCKR ADS7883SDBVR ADS7886SDBVR ADS7888SDCKR ADS7883SDBVR ADS7886SDBVR ADS7888SDCKR ADS8319IBDGSCR ADS7883SDBVT ADS788SSDBVT ADS788SDDKR A											Wafer Fab Site			
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ADS7884SDBVT	ADS7886SDCKT	ADS8318IBDGST	ADS8319IDGSR	
ADS7885SDBVR	ADS7887SDBVR	ADS8318IBDRCT	ADS8319IDGST	
ADS7885SDBVT	ADS7887SDBVT	ADS8318IDGSR	ADS8319IDRCT	
ADS7886SBDBVR	ADS7887SDCKR	ADS8318IDGST	ADS8339IDGSR	
ADS7886SBDBVT	ADS7887SDCKT	ADS8318IDRCT	ADS8339IDGST	



TI Information Selective Disclosure

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS7886SBDBVR	Qual Device: ADS7886SDCKR	Qual Device: ADS8318IBDGSR	QBS Process Reference: <u>OPA300AID</u>
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0
CDM	ESD CDM	1000 V	-	-	-	1/3/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	Pass	Pass
HAST	Biased HAST, 110C/85%RH	264 Hours	1/77/0	1/77/0		-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	3/231/0
HBM	ESD HBM	4000 V	-	-	-	1/3/0
HTOL	Life Test, 150C	300 Hours	-	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	3/135/0
HTSL	High Temp Storage Bake 170C	420 Hours	1/77/0	1/77/0	3/231/0	-
LU	Latch-up	(per JESD78)	-	-	-	1/12/0
TC	Temperature Cycle, -65/150C	500 Cycles	2/154/0	2/154/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	1/77/0	1/77/0	3/231/0	-
YLD	Yield Analysis	-	Pass	Pass	Pass	-
The following The following The following wality and En reen/Pb-free	ing was performed for Autoclave, Unbiase g g are equivalent HTOL options based on ar g are equivalent HTSL options based on ar g are equivalent Temp Cycle options per Ji rivironmental data is available at TI's exten S taturs: rree(SMT) and Green	ctivation energy of 0.7eV : 125C/1k H ctivation energy of 0.7eV : 150C/1k H ESD47 : -55C/125C/700 Cycles and	lours, 140C/480 Hours, 1 lours, and 170C/420 Hou	150C/300 Hours, and 15		

Change Number: C1806171 TI Qualification ID: 20180626-126214



Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: ADS8318IBDRCT	QBS Product Reference: ADS8318DGS	QBS Product Reference: ADS8318DRC	QBS Process Reference: <u>OPA300AID</u>
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	-	1/3/0	1/3/0	-
CDM	ESD CDM	1000 V	-	-	-	1/3/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	3/231/0	3/231/0
HBM	ESD - HBM	2500 V	-	-	1/3/0	1/3/0
HTOL	High Temp Operating Life, 155C	240 Hours	-	1/115/0	3/343/0	-
HTOL	Life Test, 150C	300 Hours	-	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	3/135/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/228/0	3/231/0	3/231/0	-
LU	Latch-up	(per JESD78)	-	-	-	1/12/0
TC	Temperature Cycle - 65/150C	500 Cycles	3/231/0	-	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47:-55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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